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2811

11/19/01
P. Walker
1-17-02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): Tae Heon LEE et al.

U.S. Serial No.: 09/687,048
U.S. Filing Date: October 13, 2000
Art Unit: 2811

Priority Claim: KR 99-44650
Priority Date: October 15, 1999

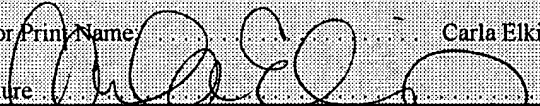
Title of Invention: LEADFRAME AND SEMICONDUCTOR
PACKAGE WITH IMPROVED SOLDER JOINT
STRENGTH

Attorney Reference: 45475-00026
99-44650

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Assistant Commissioner for Patents
Washington, D.C. 20231

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PRELIMINARY AMENDMENT
WITH REPLACEMENT SECTION UNDER RULE 1.121(b)

Applicants respectfully request the Examiner to consider the following amendment and comments.